HDP/SB/21 based on PTO/SB/21 (08-00)

- G			Applicati	on Number	10/02	9,165
TRANSMITTAL FORM		_	Filing Date First Named Inv nt r		December 20, 2001 Cheol Joon YOO	
(to be used for all correspondence after initial filing)			Group Art Unit		1722	
	_		Examiner	Name	R.B.	Davis
			Attorney I	Docket Number	2561	1-000029/US
		ENCL	OSURES (ch	eck all that apply)		-
Fee Transmittal Form		Assignment Papers (for an Application)		After Allowance Communication Group		
Fee Attached		Letter to the Official Draftsperson and Sheets of Formal Drawing(s)		LETTER SUBMITTING APPEAL BRIEF AND APPEAL BRIEF (w version of pending claims)		
		Licensing-related Papers		Ap	peal Communication to Grou otice of Appeal, Brief, Reply Brief	
After Final		Petition	Petition		☐ Pr	oprietary Information
Affidavits/declaration(s)		_	Petition to Convert to a Provisional Application		St	atus Letter
Extension of Time Request		Power of Attorney, Revocation Change of Correspondence Address			ther Enclosure(s) ease identify below):	
Express Abandonment Request		Termin	al Disclaimer			
		Request for Refund				
☐ Information Disclosure Statement		CD, Number of CD(s)				
Certified Copy of Priority Document(s)		Rema	ks			
Response to Missi Incomplete Applic						
Response to Missi Parts under 37 CF 1.52 or 1.53	ng R					
	SIGNA	ATURE OF A	PPLICANT	, ATTORNEY, C	R AGE	NT
Firm or Individual name  Harness, Dickey & Pi		Pierce, P.L.0	Pierce, P.L.C. Attorney Name John A. Castellano			Reg. No. 35,094
Signature	M	TM)				
Date	December 18,	2003	<u>.                                    </u>	1 - 1		

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS:

Cheol Joon YOO

CONF. NO.: 4604

SERIAL NO.:

10/029,165

GROUP: 1722

FILED:

December 20, 2001

EXAMINER: R. B. Davis

FOR:

CLEANER FOR MOLDING APPARATUS OF

SEMICONDUCTOR CHIP PACKAGES

## **AMENDMENT**

Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450 December 18, 2003

Dear Sir:

Responsive to the Official Action dated September 25, 2003, the following amendments and remarks are respectfully submitted in connection with the above-referenced application.

**Amendments to the claims** begin on page 2 of this paper.

Remarks begin on page of this paper.